

高加工性能

高運轉率

伺服學習振盪

30i/31i/32i-B Plus

30i/31i/32i-B

0i-F Plus

特點

- 沿進給方向搖動刀具以細斷切屑
- 防止由於切屑纏繞而產生的問題

通常的車削

纏繞中的切屑

車削

伺服學習振盪

細斷後的切屑

鑽孔

細斷前的切屑

細斷後的切屑

Servo Learning Oscillation

30i/31i/32i-B Plus 30i/31i/32i-B 0i-F Plus

Features

- Shred chips by oscillating tool in feed direction
- Prevent trouble caused by entangled chips

Turning

Without oscillation

Tool moves only in one direction

Graph: Z vs Time (straight red line)

Entangled chips

Servo Learning Oscillation

Tool moves with oscillation

Graph: Z vs Time (blue wavy line)

Shredded chips

Drilling

Feed Axis

Connected chips

Oscillation

Tool moves with oscillation

Graph: Z vs Time (blue wavy line)

Shredded chips